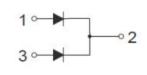


Features

- · High current capability
- Low forward voltage drop
- · Low power loss, high efficiency
- High surge capability
- · High temperature soldering guaranteed
- Mounting position: any

2 more of the same of the same

TO-252-2L



Package Marking and Ordering Information

Product ID		Pack	Marking	Qty(PCS)		
MBI	RD10xxCT-13	TO-252-2L	MBRD10★	2500		

★:From 40-200CT

Maximum Ratings Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified

ratings at 25 C ambient temperatur	C difficos (Juliel Wise 3	pecified					_
Characteristics	Symbol	MBRD 1040CT	MBRD 1045CT	MBRD 1060CT	MBRD 10100CT	MBRD 10150CT	MBRD 10200CT	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	40	45	60	100	150	200	V
Maximum RMS voltage	V _{RMS}	28	32	42	70	105	140	V
Maximum DC Blocking Voltage	V _{DC}	40	45	60	100	150	200	V
Maximum Average Per diode Forward Rectified Current Per device	I _{F(AV)}				5 10			А
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) Per leg	I _{FSM}			10	00			А
Max Instantaneous Forward Voltage at 5.0 A Per leg	V _F	0.7	7 0	0.75	0.85	0.90	0.92	V
Maximum DC Reverse Current $T_a = 25^{\circ}$ C at Rated DC Reverse Voltage $T_a = 125^{\circ}$ C	I _R		0.1 20			0.05 20		mA
Typical Junction Capacitance (1)	C _j	60	0		40	0		pF
Typical Thermal Resistance (2)	R _{θJA}	35					°C/W	
Operating Junction Temperature Range	T _j		-55 ~	+150		-55 ~ -	+175	°C
Storage Temperature Range	T _{stg}		-55 ~	+150		-55 ~ -	+175	°C
						1		

⁽¹⁾Measured at 1 MHz and applied reverse voltage of 4 V D.C

⁽²⁾P.C.B. mounted with 10cmX10cmX1mm copper pad areas.



Typical Characteristics

Fig.1 TYPICAL FORWARD CURRENT DERATING CURVE

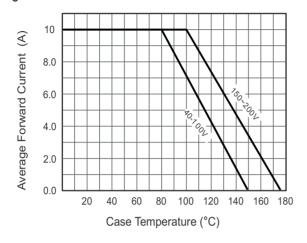


Fig.3 Typical Forward Characteristic

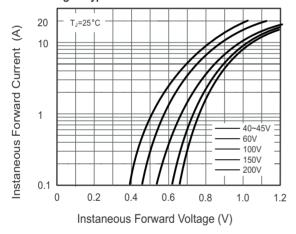


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

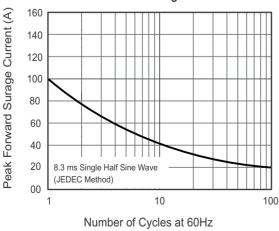
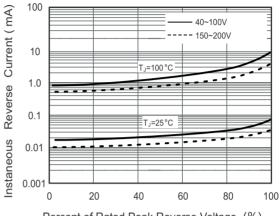


Fig.2 Typical Reverse Characteristics



Percent of Rated Peak Reverse Voltage (%)

Fig.4 Typical Junction Capacitance

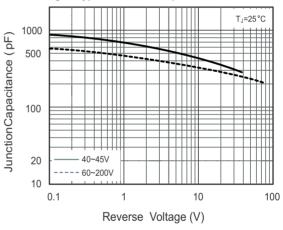
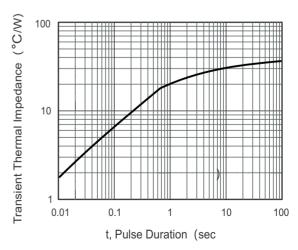
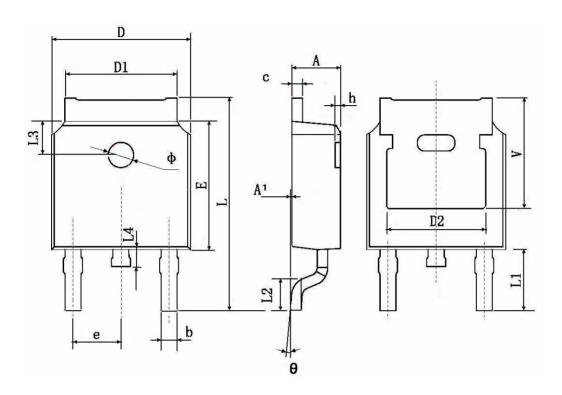


Fig.6- Typical Transient Thermal Impedance





TO-252-2L Package Information



Council of	Dimensions In	Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	



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